

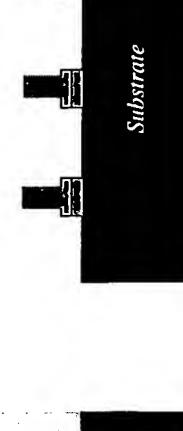
first-level metallization.

Substrate

5. Polish with coarse grain size followed by fine



6. Strip photoresist molds and follow with cure



2. Metallize and lift-off to define pads

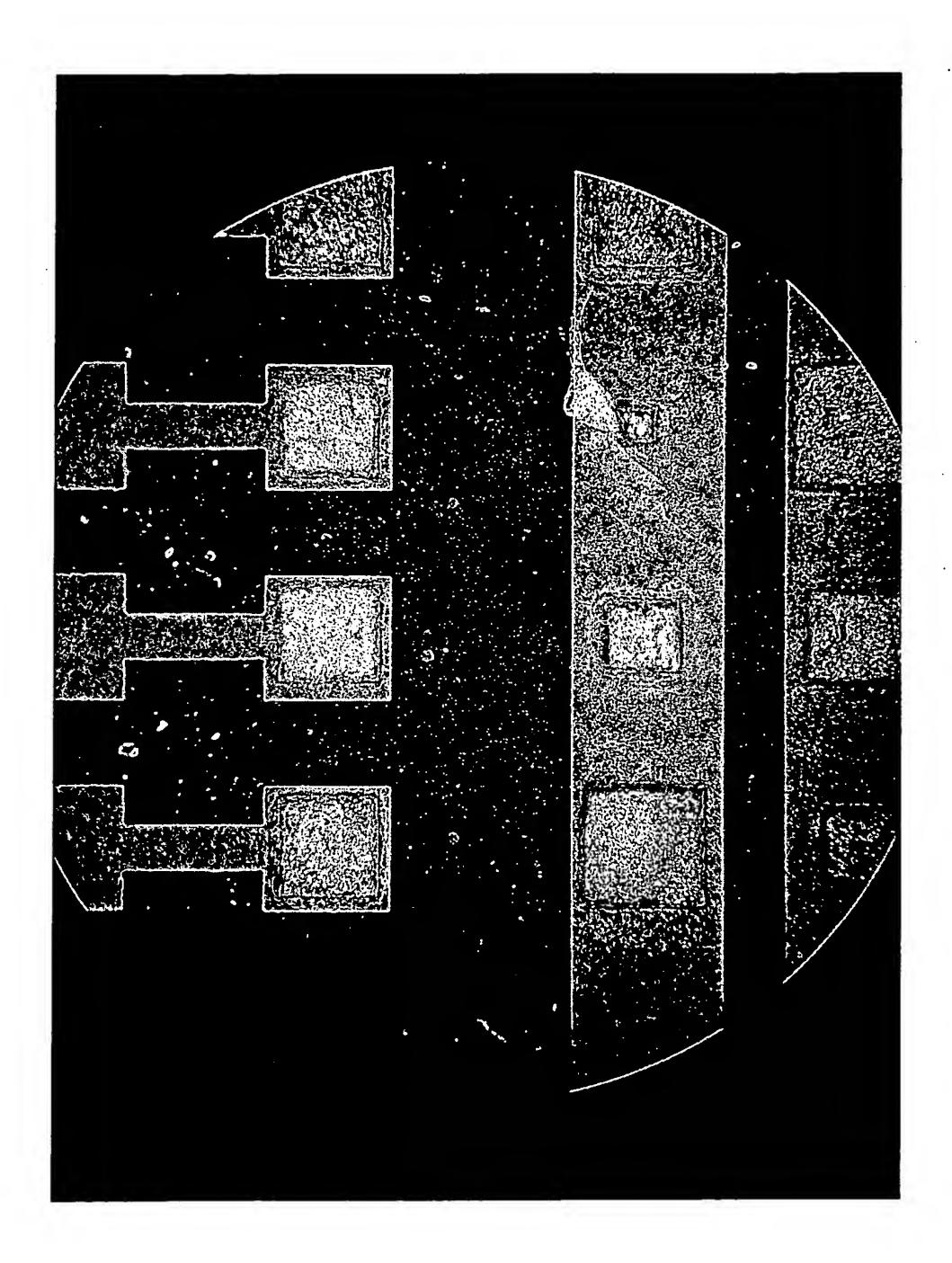


3. Pattern thick photoresist for second level



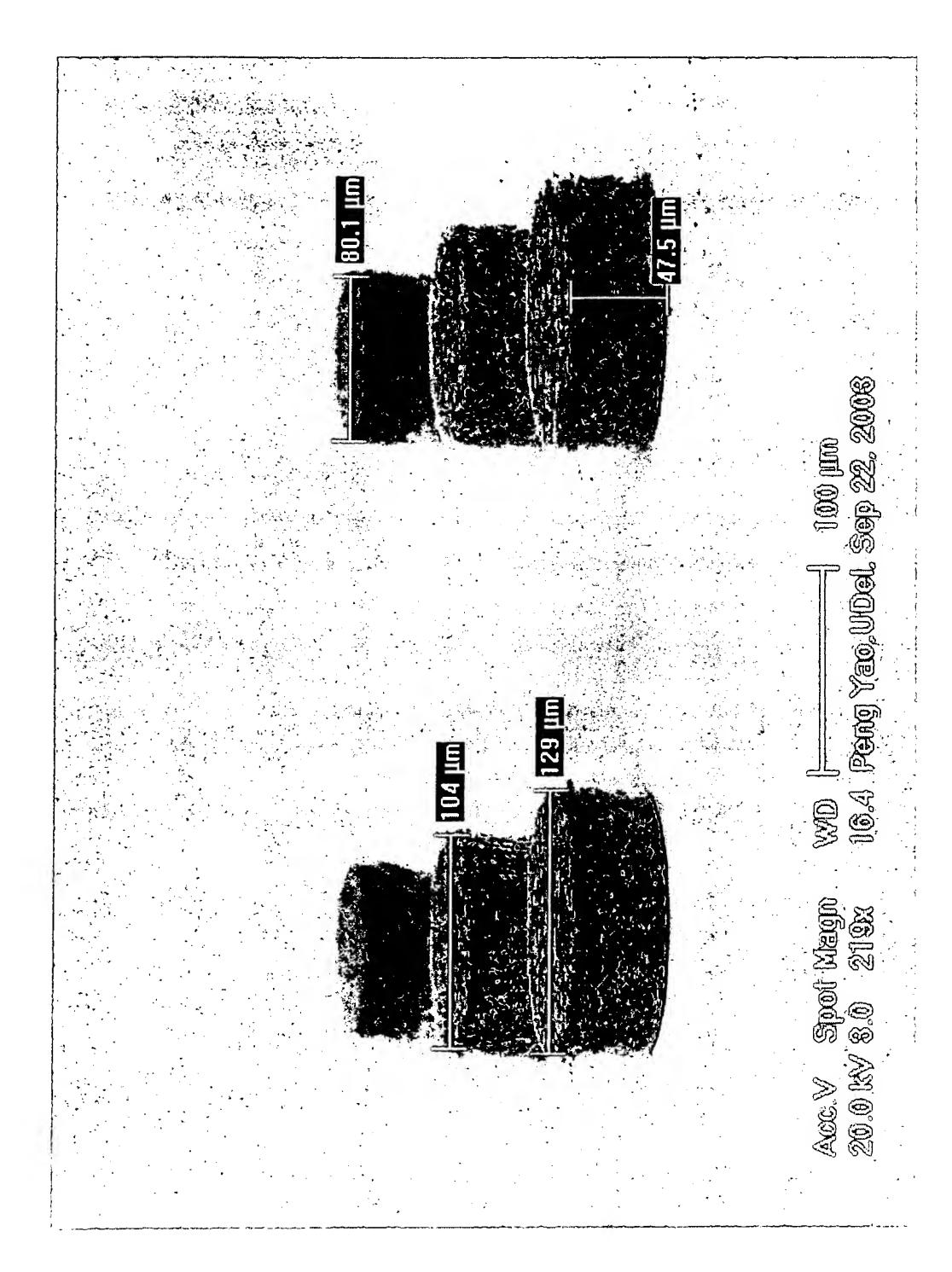
Fabrication Steps Fig.1

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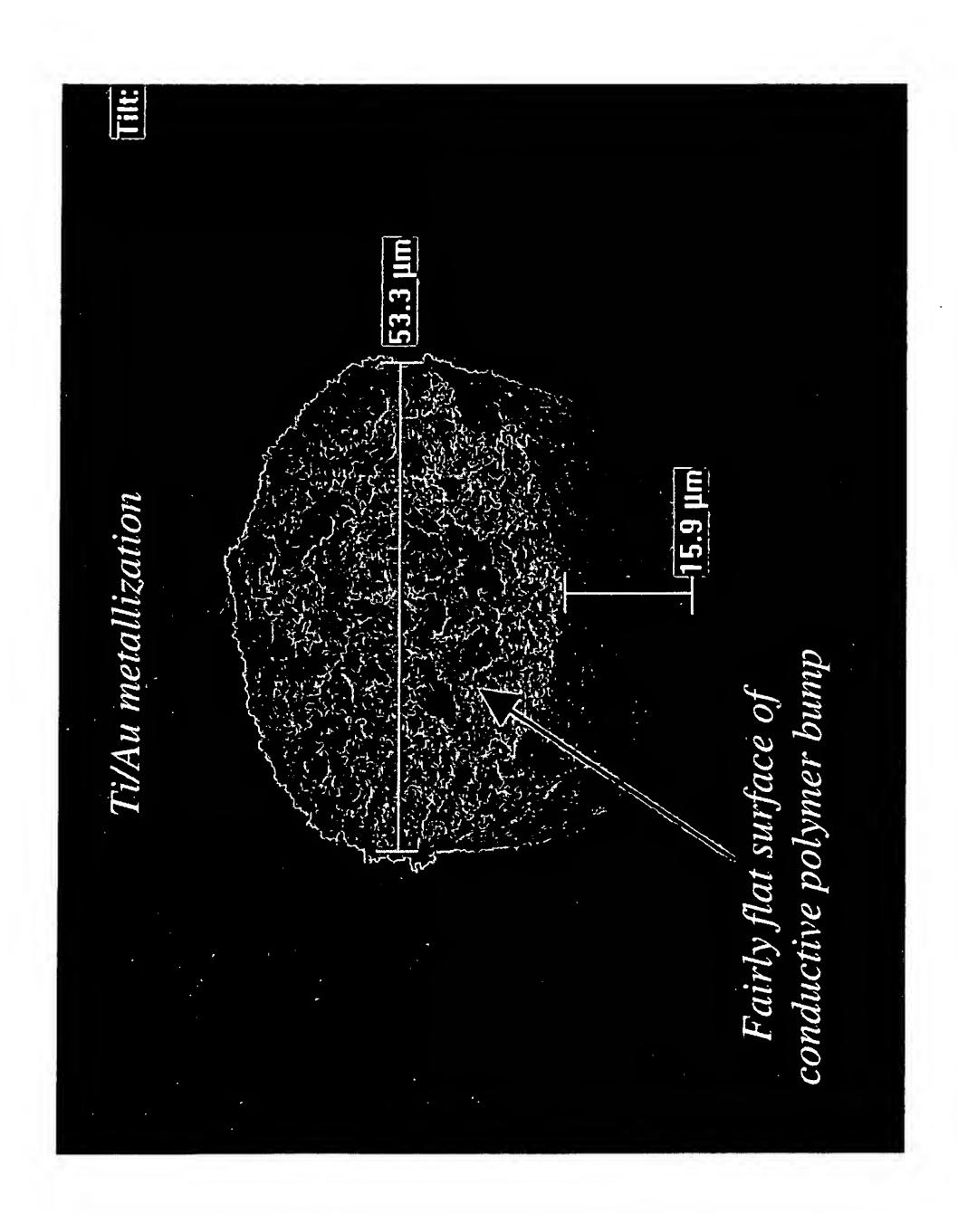


mps Under Optical Microscope

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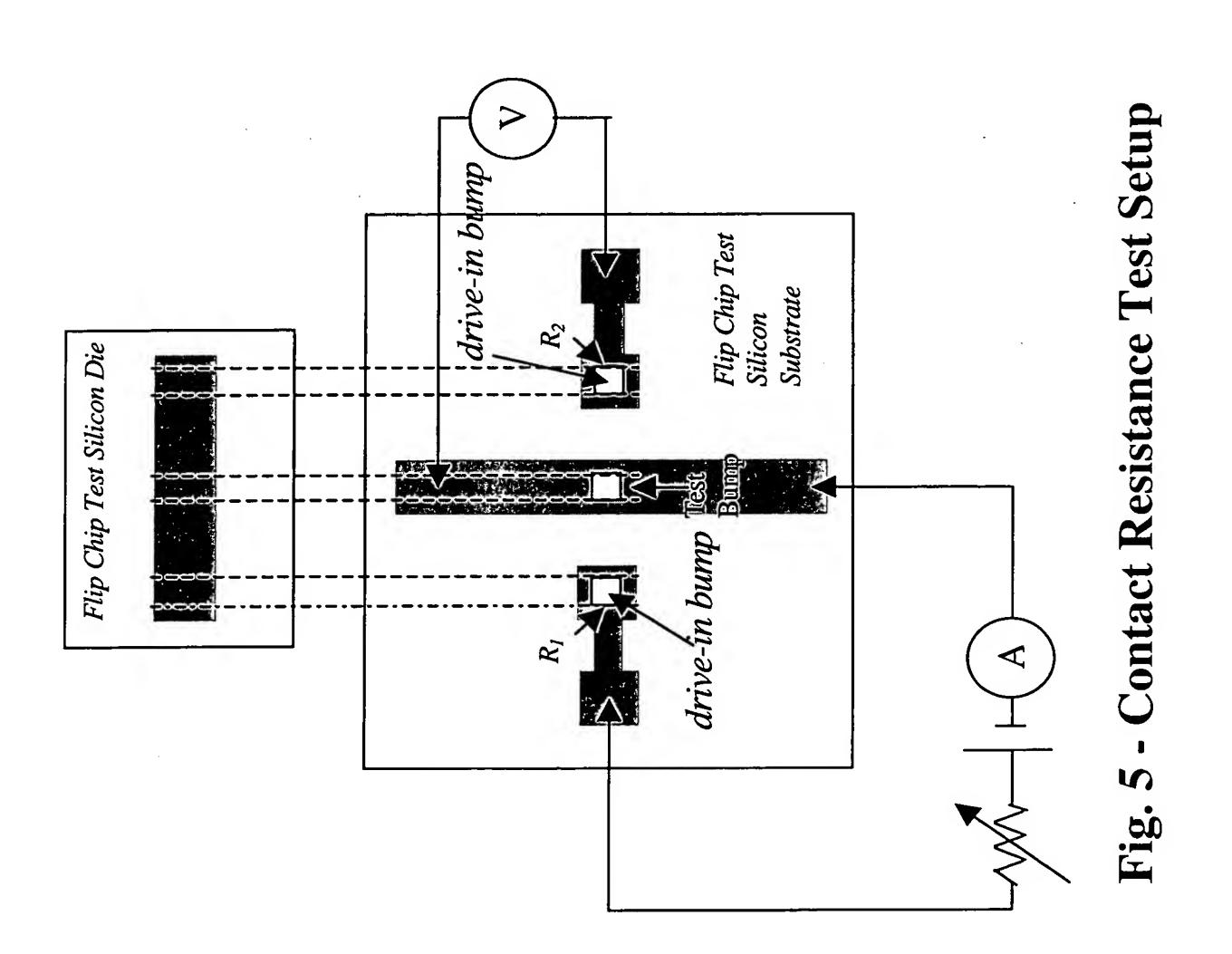


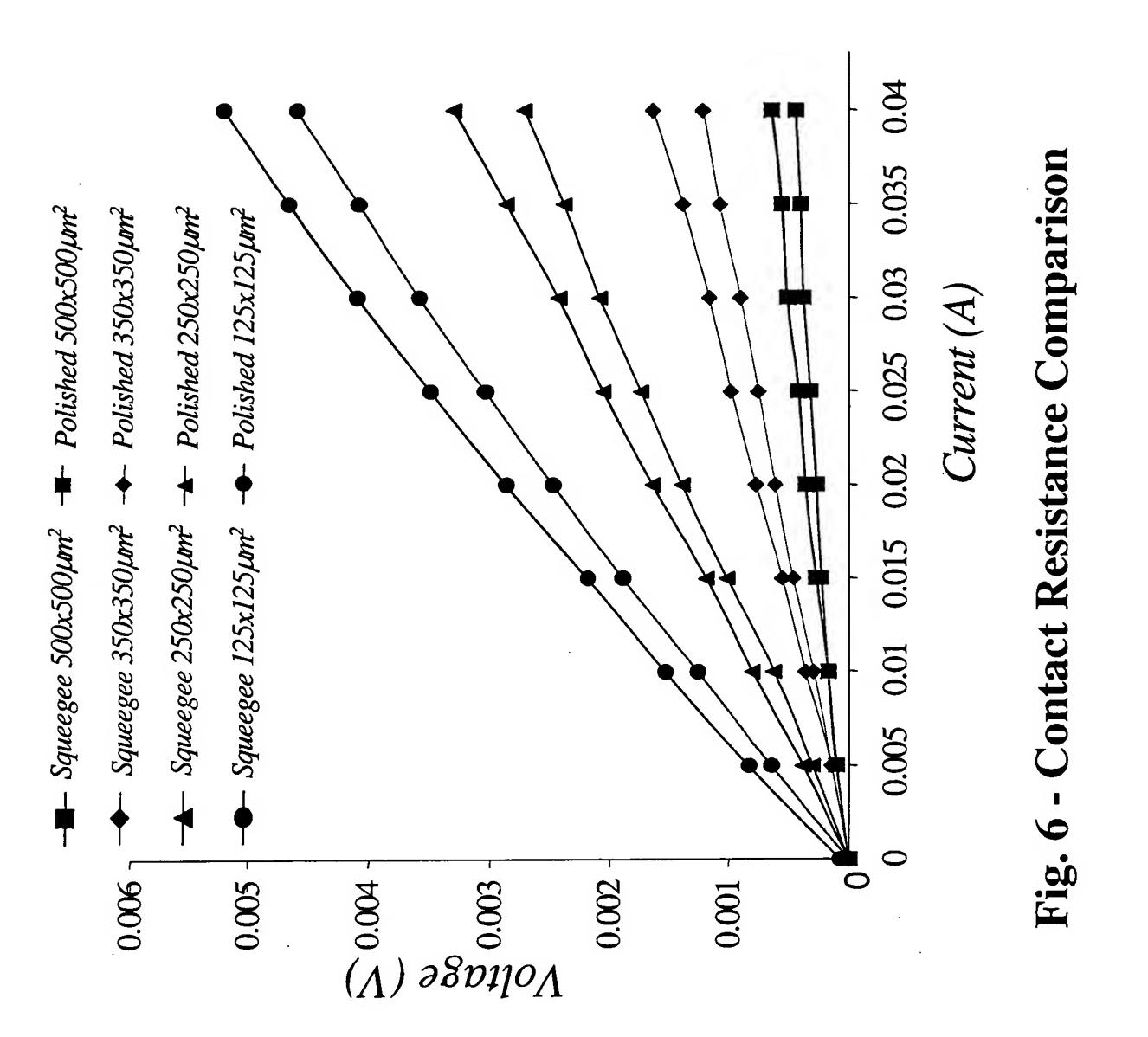
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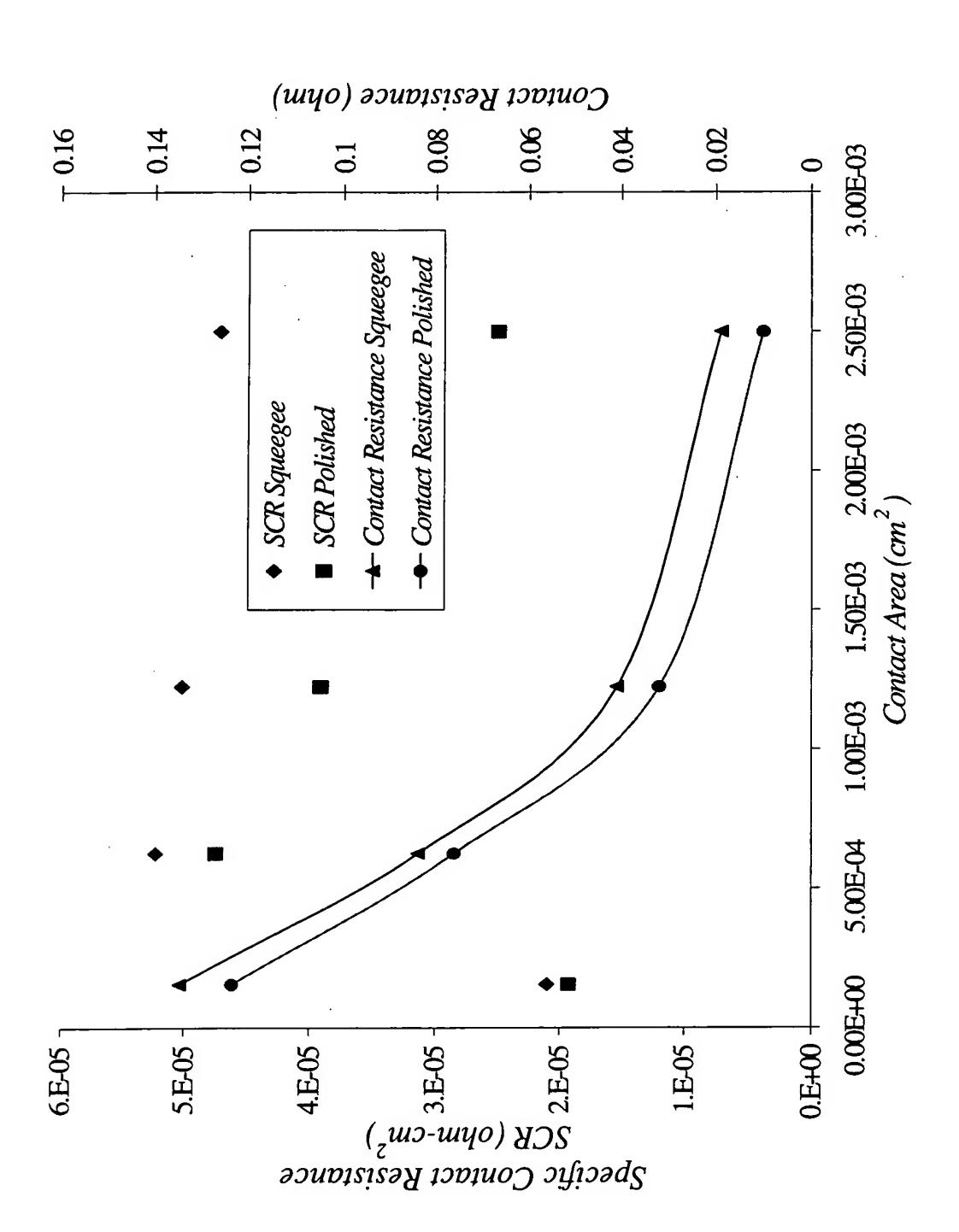
of Polished Conductive Polymer Bumps Fig. 4 - SEM View of Surface

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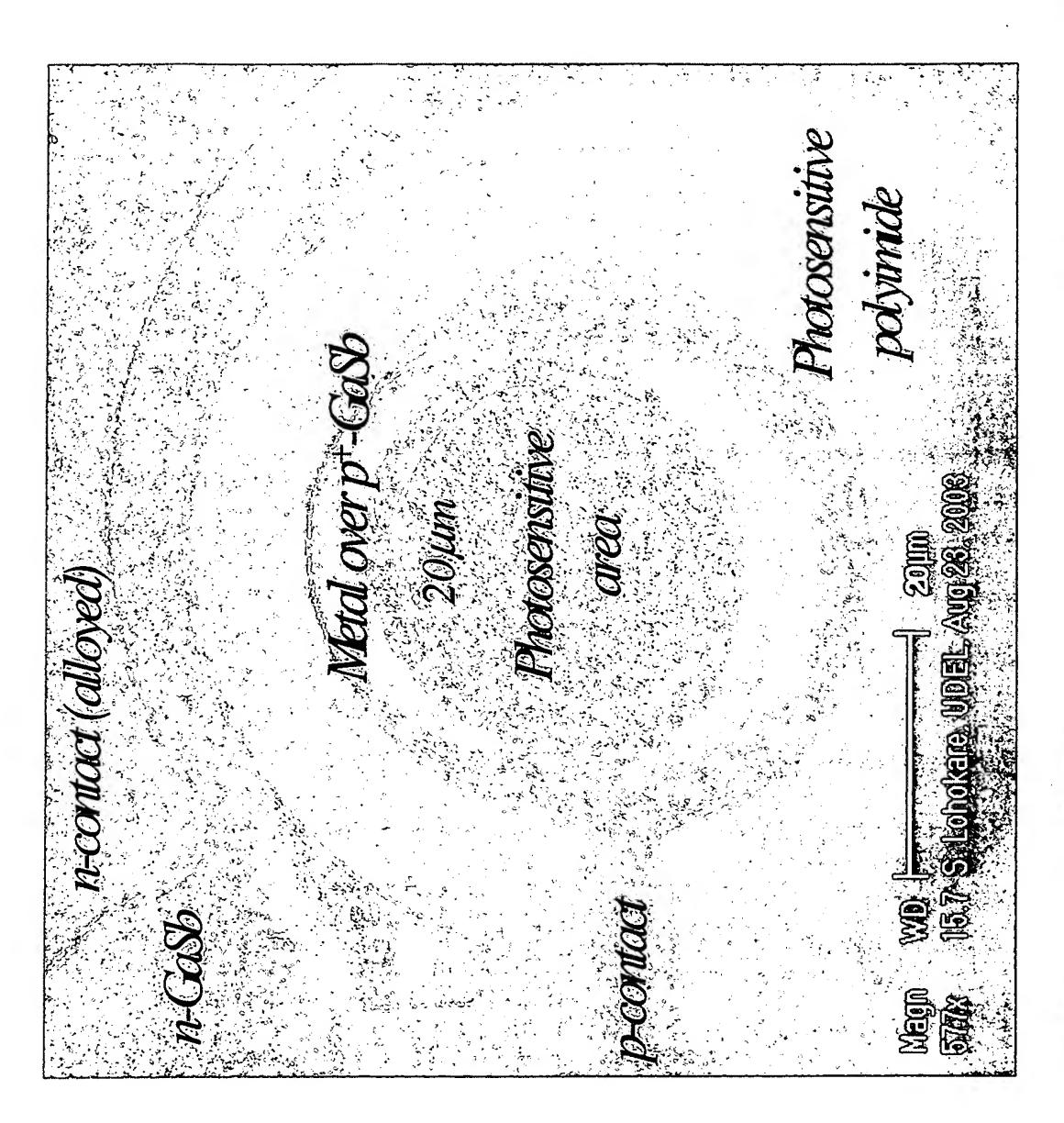






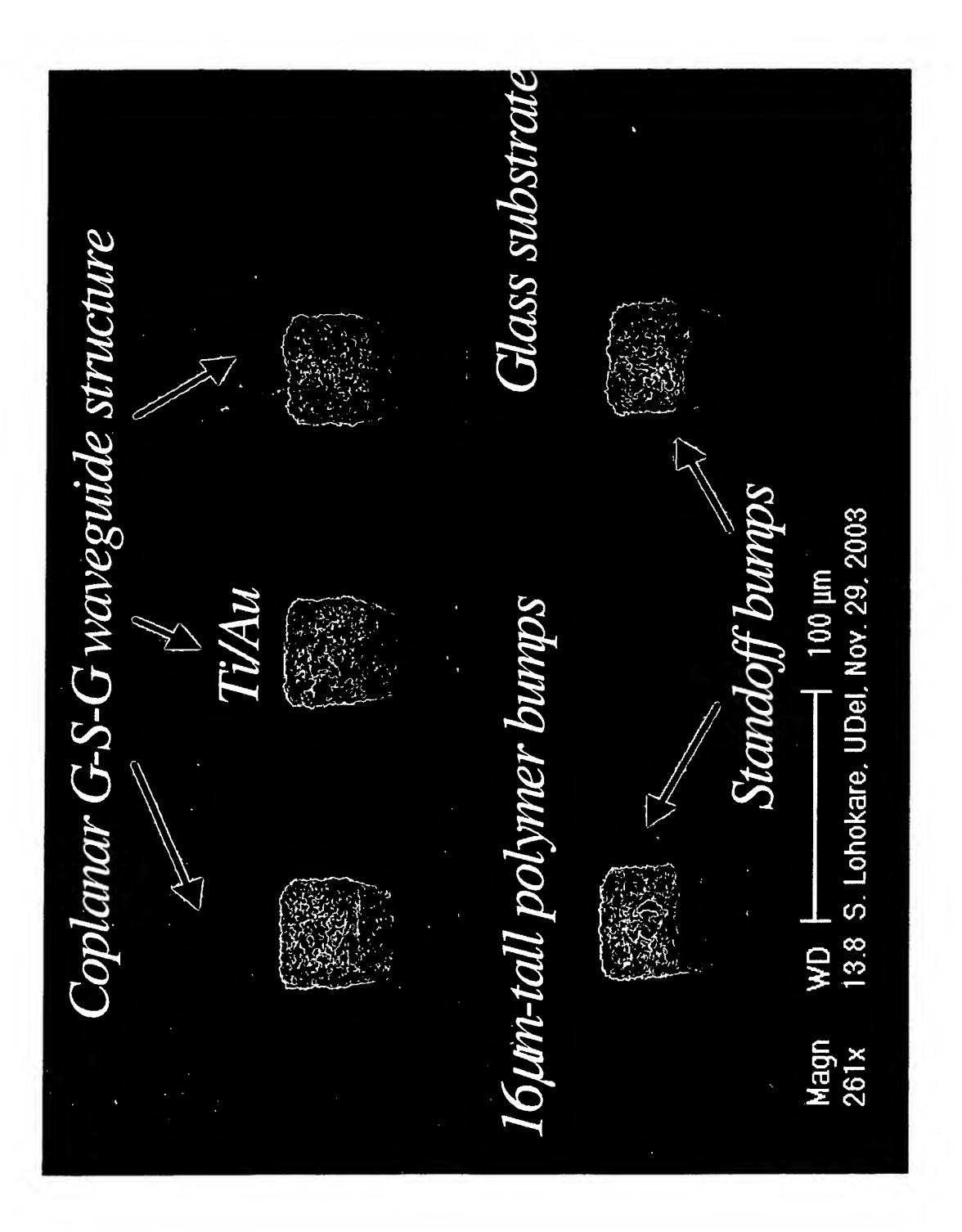


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GaAsSb/AlGaSb p-i-n Photodetect SEM View of Al

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e Adhesive Bumps on Coplanar Waveguide **SEM View of Conductive** Fig. 9

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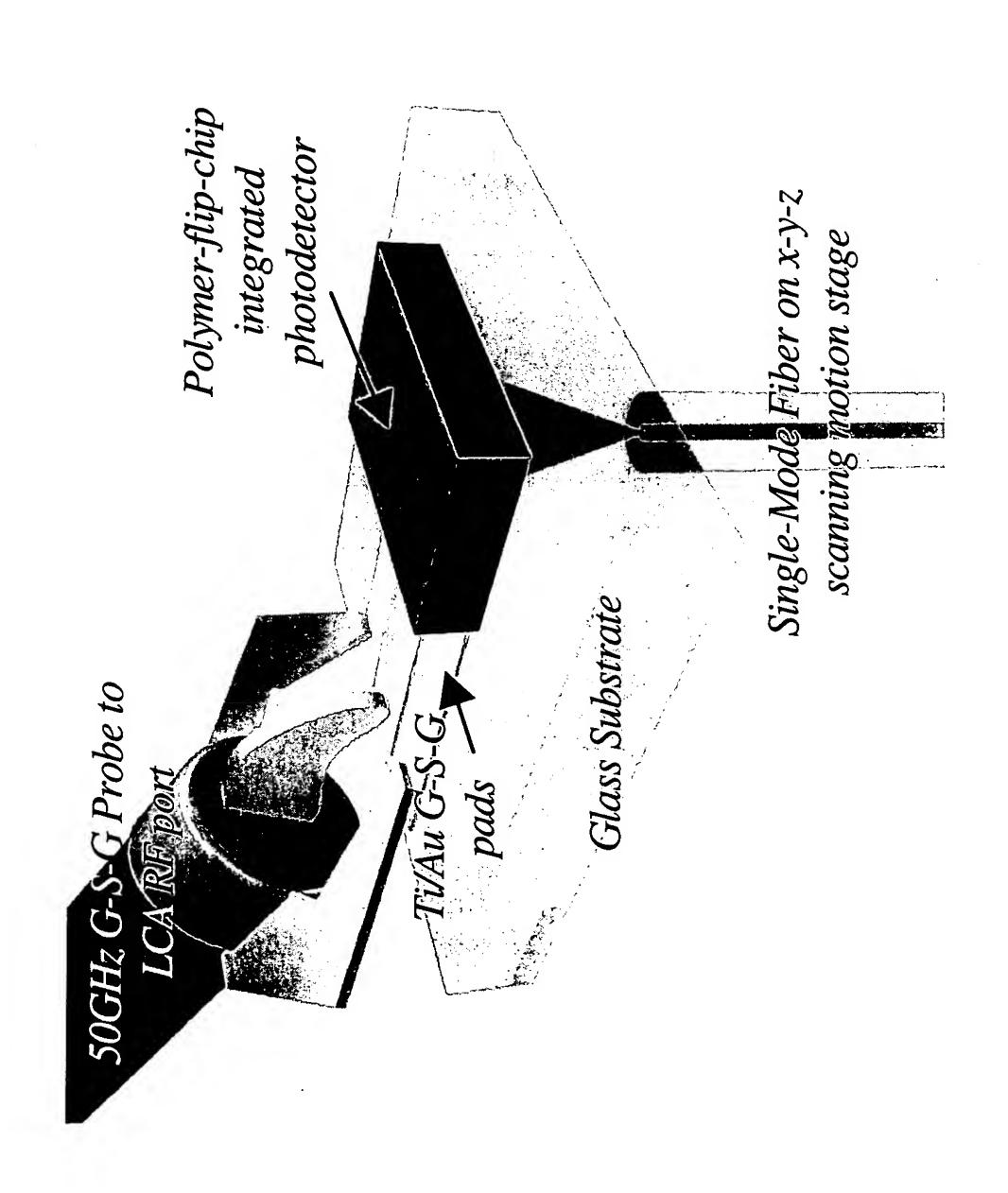
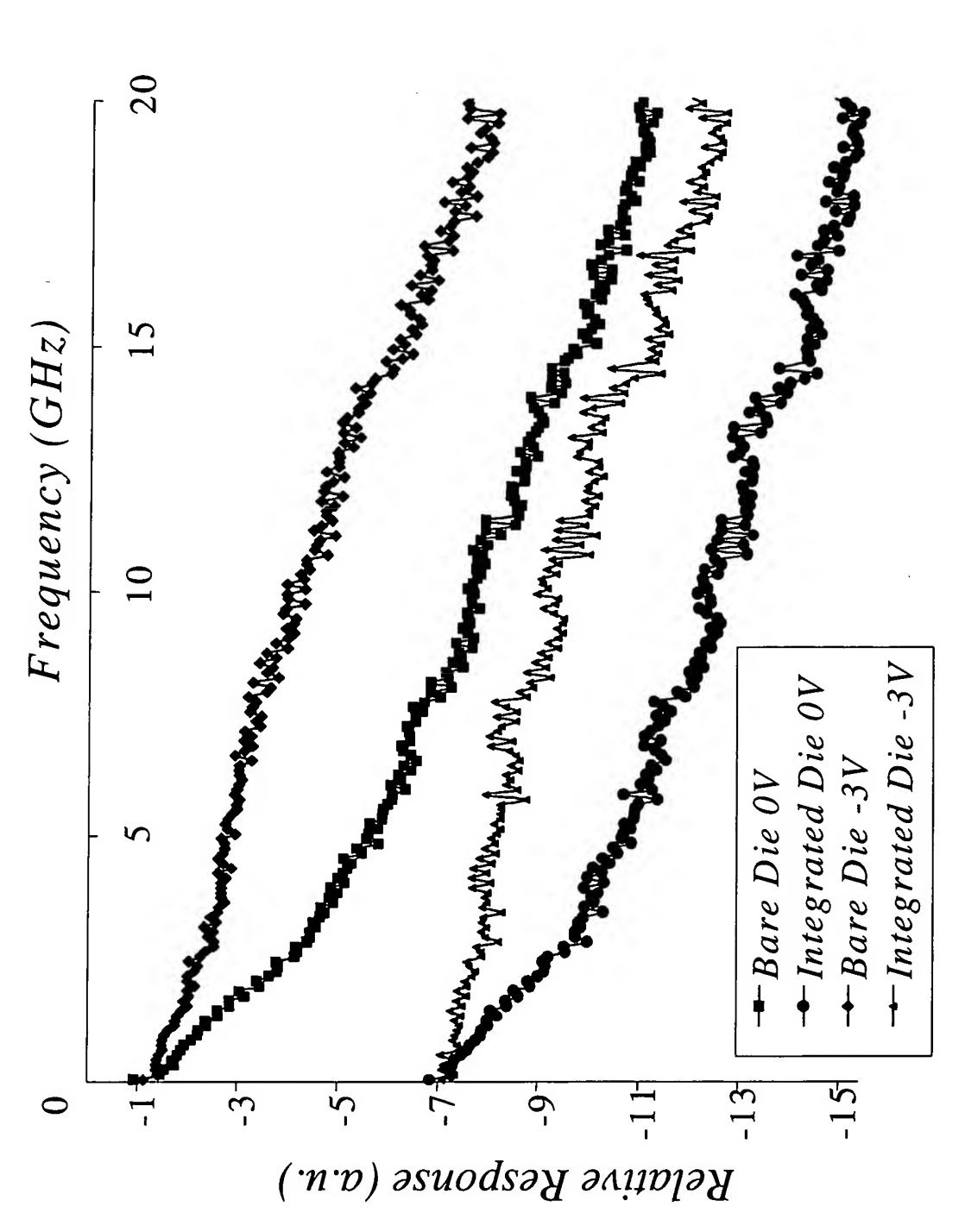


Fig. 10 – Schematic of Test Setup for PFC Integrated p-i-n Detector



onse for Bare-Die and PFC Integrated p-i-n Detector Normalized BW Resp Fig.

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